



Product Change Notification / RMES-22JKYM836

Date:

22-Jan-2021

Product Category:

Memory

PCN Type:

Manufacturing Change

Notification Subject:

CCB 4270 Final Notice: Qualification of GTK as a new assembly site for selected Atmel products available in 28L SOIC (.300in) package.

Affected CPNs:

[RMES-22JKYM836_Affected_CPN_01222021.pdf](#)
[RMES-22JKYM836_Affected_CPN_01222021.csv](#)

Notification Text:

PCN Status:Final notification

PCN Type:Manufacturing Change

Microchip Parts Affected:Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:Qualification of GTK as a new assembly site for selected Atmel products available in 28L SOIC (.300in) package.

Pre Change:Assembled at LPI using CRM-1033BF die attach, QI-4939 die coat and G600 molding compound material

Post Change:Assembled at GTK using EN-4900GC die attach, PIX-8144 die coat and G631M molding compound material

Pre and Post Change Summary:

	Pre Change	Post Change
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Method to Identify Change:Traceability code

Qualification Report:Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:June 23, 2020: Issued initial notification.**January 22, 2020:** Issued final notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_RMES-22JKYM836 Qual Report.pdf](#)

[PCN_RMES-22JKYM836_Packing Pre and Post Change.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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MICROCHIP

QUALIFICATION REPORT SUMMARY

PCN#: RMES-22JKYM836

Date:

January 8, 2021

**Qualification of GTK as a new assembly site for selected
Atmel products available in 28L SOIC (.300in) package.**



MICROCHIP PACKAGE QUALIFICATION REPORT

Purpose: Qualification of GTK as a new assembly site for selected Atmel products available in 28L SOIC (.300in) package.

Misc.	Assembly site	GTK
	BD Number	NA
	MP Code (MPC)	198027N3XC07
	Part Number (CPN)	AT28C256-15SU
	MSL Information	MSL 3 / 260
	Assembly Shipping Media (T/R, Tube/Tray)	Tube
	Base Quantity Multiple (BQM)	27 units/tube
	Reliability Site	MPHIL
	CCB	4270
	Qual Report	QTP4294 Rev. A
Lead-Frame	Paddle Size	190 x 340
	Material	A194
	DAP Surface Prep	DOUBLE RING
	Treatment	None
	Process	Etched
	Lead-lock	No
	Part Number	11-0228W-202
	Lead Plating	Matte Sn
	Strip Size	4X8
	Srip Density	32
Bond Wire	Material	Au
Die Attach	Part Number	EN-4900GC
	Conductive	Yes
MC	Part Number	G600F
PKG	PKG Type	SOIC
	Pin/Ball Count	28L
	PKG width/size	300mils



MICROCHIP PACKAGE QUALIFICATION REPORT

Manufacturing Information

Assembly Lot No.
GTK-212100024.000
GTK-212100025.000
GTK-212100026.000

Result

Pass Fail _____

300 mils SOIC28L (N3X) Mask 19802 using Au wire at GTK Taiwan is qualified the Moisture/Reflow Sensitivity Classification Level 3 at 260°C reflow temperature per IPC/JEDEC J-STD-020E standard. No delamination observed on all the units.

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
<u>Precondition</u> <u>Prior Perform</u> <u>Reliability</u> <u>Tests (At MSL</u> <u>Level 3)</u>	Electrical Test :25°C, 85°C System: EPRO – MT9308	JESD22-A113 231 units of 3 Lots	864(0)	0/864	Pass	
	0hr CSAM	45 units of 3 Lots	135(0)	0/135	Pass	
	Bake 150°C, 24 hrs System:		864(0)			
	30°C/60%RH Moisture Soak 192 hrs. System: Climats Excal 5423-HE	IPC/JED EC J- STD- 020E	864(0)			
	3x Convection-Reflow 260°C max System: Mancorp CR.5000F		864(0)	0/864	Pass	
	Post CSAM	45 units of 3 Lots	135(0)	0/135	Pass	
	Electrical Test : 25°C, 85°C System: EPRO – MT9308		864(0)	0/864	Pass	

PACKAGE QUALIFICATION REPORT

Qual Report : QTP4294

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
High Temperature Storage Life	Stress Condition: (Standard) Bake 175°C, 504 hrs System : VOTSCH VT 7012 S2 Electrical Test :25°C, 85°C System: EPRO – MT9308	JESD22-A104 45 units of 1 Lots	45(0) 45(0)	0/45	Pass	
Thermal Cycles	Stress Condition: (Standard) -65°C / 150°C , 500cycles System: Electrical Test: 85°C System: EPRO – MT9308 Bond Strength: Wire/Stitch Pull Bond Shear 30 bonds from 5 units / Lot (3 Lots)	JESD22-A104 77 units of 3 Lots	231(0) 231(0)	231(0)	Pass Pass	
Unbiased HAST	Stress Condition: (Standard) 130°C / 80°C, 96hours System: Electrical Test: 25°C, 85°C System: EPRO – MT9308	JESD22-A104 77 units of 3 Lots	231(0) 231(0)	231(0)	Pass	
Biased HAST	Stress Condition: (Standard) 130°C / 80°C, 96hours System: Electrical Test: 25°C, 85°C System: EPRO – MT9308	JESD22-A104 77 units of 3 Lots	231(0) 231(0)	231(0)	Pass	

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PACKAGE QUALIFICATION REPORT

Qual Report : **QTP4294**

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Bond Strength Data Assembly	Wire /Stitch Pull:	M2011.8	35(0)	0/35	Pass	
	Bond Shear:	MIL-STD-883	35(0)	0/35	Pass	
Package Dimension	30 units from 3 Lots (10 units per lot)	JESD22- B100/B108	30(0)	0/30	Pass	

CCB 4270
Pre and Post Change Summary
PCN#: RMES-22JKYM836




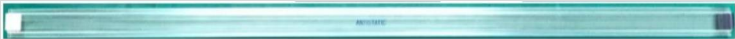


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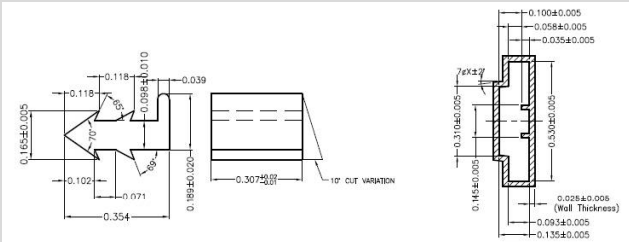
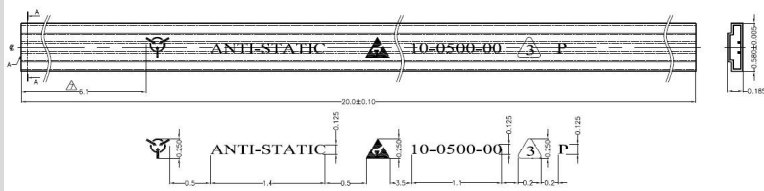
SMART | CONNECTED | SECURE

Packing Information (Tube Comparison)

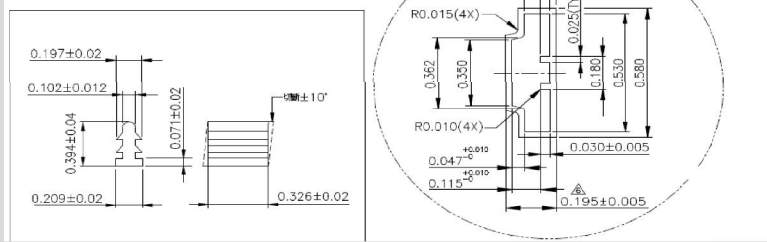
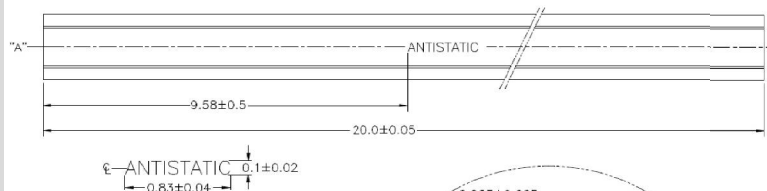
PRE-CHANGE (LPI)						POST-CHANGE (GTK)					
											
											
Package	Lead Count	Body Size	Units/Tube	Length (inch)	End Plugs	Package	Lead Count	Body Size	Units/Tube	Length (inch)	End Plugs
SOIC	28	300 mils	27	20+/-0.10	Black/Black	SOIC	28	300 mils	27	20 +/- 0.05	Blue/White

Tube Drawing

PRE-CHANGE (LPI)



POST-CHANGE (GTK)



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Affected Catalog Part Numbers(CPN)

- AT28HC256-70SU
- AT28HC256-90SU
- AT28HC256-12SU
- AT28HC256E-90SU
- AT28HC256E-12SU
- AT28HC256F-90SU
- AT28C256-15SU
- AT28C256E-15SU
- AT28C256F-15SU
- AT28BV256-20SU
- AT28HC256E-70SU-T
- AT28HC256-70SU-T
- AT28HC256-90SU-T
- AT28HC256-12SU-T
- AT28HC256E-90SU-T
- AT28HC256E-12SU-T
- AT28HC256F-90SU-T
- AT28C256-15SU-T
- AT28C256E-15SU-T
- AT28C256F-15SU-T
- AT28BV256-20SU-T